

**English Abstract of Cited Device 3**  
**[Korean Registered Patent Publication No. 195,222 (Feb. 11, 1999)]**

**TITLE: WAFER POLISHING DEVICE**

**Abstract:**

The subject invention relates to a wafer polishing device. In the polishing device according to the subject invention, a retaining ring installed in a wafer carrier comprises an inner surface apart from a carrier film as much as a predetermined distance and a bottom surface located on the same horizontal surface as the surface to be polished of a wafer to be loaded on the wafer carrier surface. A plurality of slots are formed at the bottom surface toward a radius direction to move freely between the outer side and the inner side of the retaining ring. At the time of polishing a wafer by CMP process using the polishing device according to the subject invention, the polishing can be accomplished uniformly on the whole surface of the wafer.